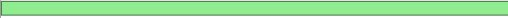






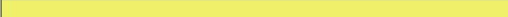





# Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.40mil	3.5
4		Component Side	Copper	1.40mil	
5		Dielectric 1	FR-4	12.60mil	4.8
6		GND	Copper	1.42mil	
7		Dielectric 3		5.00mil	4.2
8		NEW_POWER	Copper	1.42mil	
9		Dielectric 4		10.00mil	4.2
10		Solder Side	Copper	1.40mil	
11		Bottom Solder	Solder Resist	0.40mil	3.5
12		Bottom Overlay			
13		Bottom Paste			
	Height : 34.03mil				